



SOT954-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 1.35 x 1.7 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-8-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.6	-	1.7	1.8	mm
E	package width		1.25	-	1.35	1.45	mm
A	seated height		[tbd]	-	0.85	1	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	8	-	

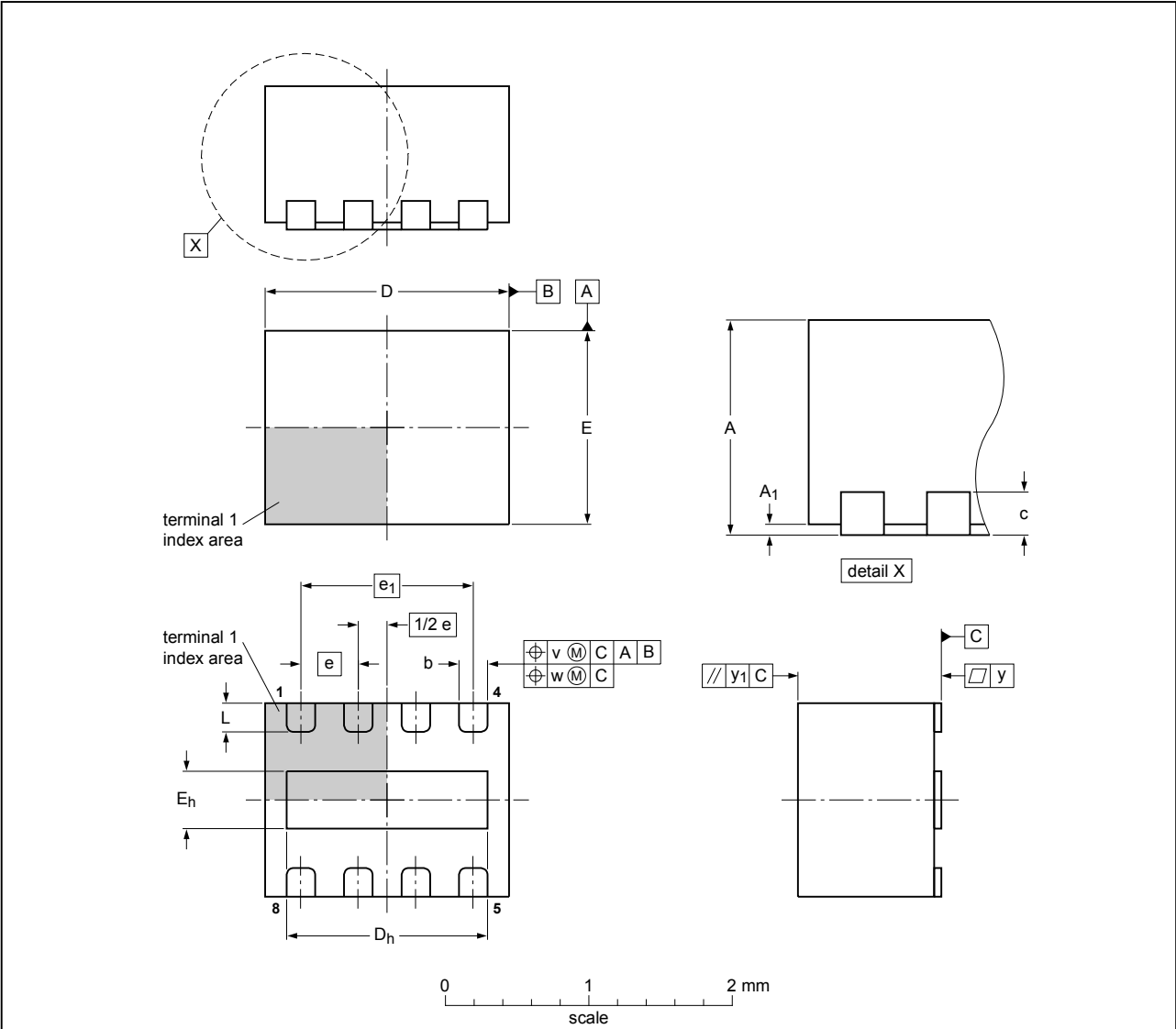


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2. Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads;
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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	b	c	D	D _h	E	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.25 0.15	0.2	1.8 1.6	1.55 1.25	1.45 1.25	0.55 0.25	0.4	1.2	0.3 0.1	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT954-1						06-07-05 06-08-25

Fig. 1. Package outline HVSON8 (SOT954-1)

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3. Legal information

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